

Type number	Package	Package description	Total product weight
BCV27	SOT23	TO-236AB	7.64678 mg

12NC	Version	Pb-free soldering			Pb soldering			Number of processing cycles	Assembly site	RHF-indicator
		MSL	PPT	MPPT	MSL	PPT	MPPT			
933806220215	14	1	260	30 s	1	235	20 s	3	Seremban, Malaysia; Dongguan, China; D-22529 HAMBURG, Germany	

Subpart	Material group	Substances	CAS number	Mass(mg)	Mass(%) of subpart	Mass(%) of total product	
Die	Doped silicon	Silicon (Si)	7440-21-3	0.20000	100.00000	2.61548	
		subTotal		0.20000	100.00000	2.61548	
Lead Frame	Iron-nickel alloy	Aluminium (Al)	7429-90-5	0.00220	0.09000	0.02884	
		Carbon (C)	7440-44-0	0.00098	0.04000	0.01282	
		Chromium (Cr)	7440-47-3	0.00539	0.22000	0.07049	
		Cobalt (Co)	7440-48-4	0.01054	0.43000	0.13777	
		Iron (Fe)	7439-89-6	1.17551	47.98000	15.37261	
		Manganese (Mn)	7439-96-5	0.02107	0.86000	0.27554	
		Misc. Sulfur compounds (generic)	7704-34-9	0.00049	0.02000	0.00641	
		Misc. phosphorus compounds (generic)		0.00049	0.02000	0.00641	
		Nickel (Ni)	7440-02-0	0.88543	36.14000	11.57912	
		Silicon (Si)	7440-21-3	0.00637	0.26000	0.08330	
	Pure metal layer	Copper (Cu)	7440-50-8	0.27856	11.37000	3.64291	
		Silver (Ag)	7440-22-4	0.06296	2.57000	0.82342	
		subTotal		2.45000	100.00000	32.03964	
Mould Compound	Additive	Non hazardous	Proprietary	0.13862	2.90000	1.81279	
		Triphenylphosphine	603-35-0	0.00239	0.05000	0.03125	
	Filler	Silica -amorphous-	7631-86-9	3.44160	72.00000	45.00718	
	Polymer	Pigment	Carbon black	1333-86-4	0.00239	0.05000	0.03125
		Epichlorohydrin/o-Cresol/Formaldehyde polymer (generic)	29690-82-2	0.71700	15.00000	9.37650	
	Phenol Formaldehyde resin (generic)	9003-35-4	0.47800	10.00000	6.25100		
	subTotal			4.78000	100.00000	62.50997	
Post-Plating	Impurity	Antimony (Sb)	7440-36-0	0.00002	0.01000	0.00027	
		Bismuth (Bi)	7440-69-9	0.00004	0.02000	0.00055	
		Iron (Fe)	7439-89-6	0.00002	0.01000	0.00027	
		Lead (Pb)	7439-92-1	0.00002	0.01000	0.00027	
	Tin solder	Tin (Sn)	7440-31-5	0.20990	99.95000	2.74488	
		subTotal		0.21000	100.00000	2.74624	
Wire	Pure metal	Copper (Cu)	7440-50-8	0.00678	100.00000	0.08866	
		subTotal		0.00678	100.00000	0.08866	

Note(s):

1) This is a generic description of the substance used as the actual composition of the substances are either considered proprietary or no official CAS number is available. If a CAS number is given, it is the closest match available.

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